Silicon NPN Epitaxial

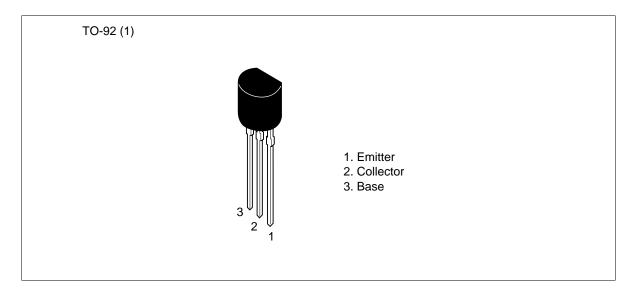
# **HITACHI**

ADE-208-1053 (Z) 1st. Edition Mar. 2001

## Application

Low frequency low noise amplifier

#### **Outline**





#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

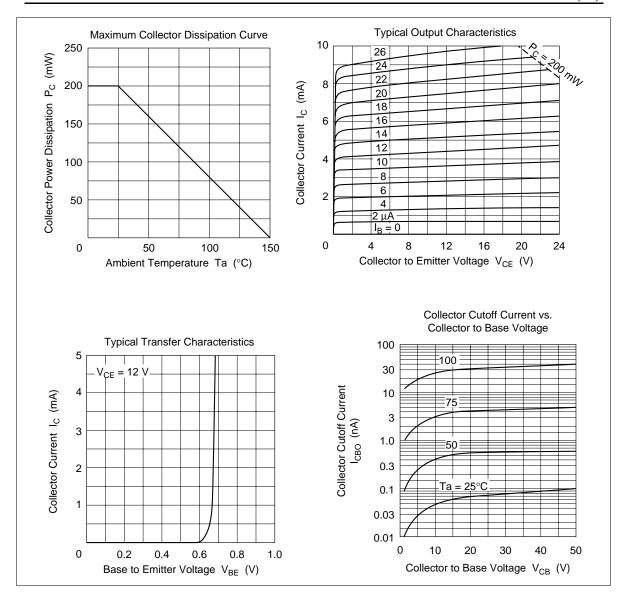
Item	Symbol	Ratings	Unit	
Collector to base voltage	$V_{CBO}$	55	V	
Collector to emitter voltage	$V_{\text{CEO}}$	50	V	
Emitter to base voltage	$V_{EBO}$	5	V	
Collector current	I <sub>c</sub>	100	mA	
Collector power dissipation	P <sub>c</sub>	200	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

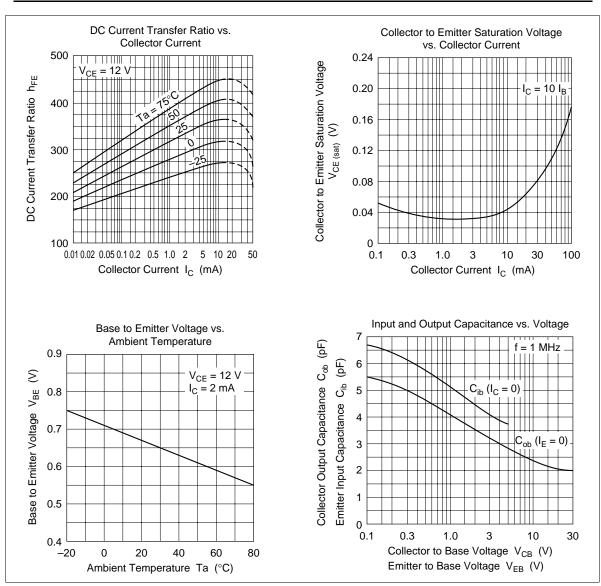
#### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

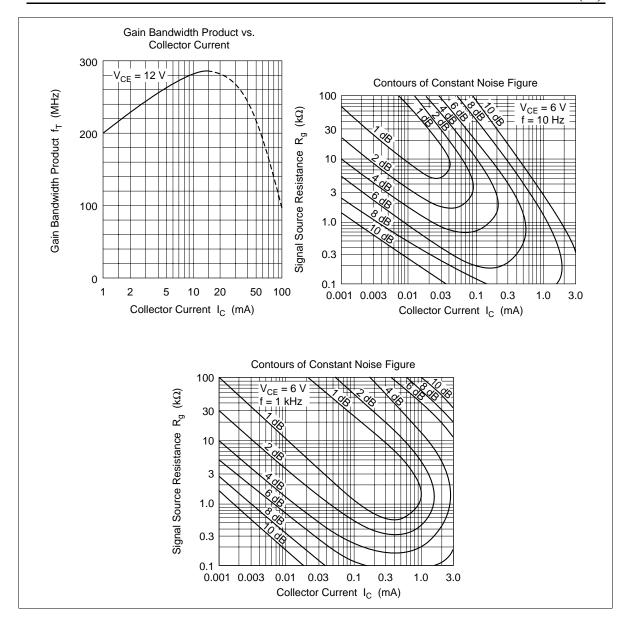
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	55	_	_	V	$I_{c} = 10 \ \mu\text{A}, \ I_{e} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	_	_	V	$I_{C} = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_{E} = 10 \mu A, I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	0.5	μΑ	$V_{CB} = 18 \text{ V}, I_{E} = 0$
Emitter cutoff current	I <sub>EBO</sub>	_	_	0.5	μΑ	$V_{EB} = 2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h <sub>FE</sub> *1	250	_	1200		$V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$
Base to emitter voltage	V <sub>BE</sub>	_	_	0.75	V	$V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE}(\text{sat})}$	_	_	0.5	V	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$
Collector output capacitance	Cob	_	2.3	3.5	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$
Gain bandwidth product	f <sub>T</sub>	_	230	_	MHz	$V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$
Noise figure	NF	_	_	8	dB	$V_{CE} = 6 \text{ V}, I_{C} = 0.1 \text{ mA},$ $f = 10 \text{ Hz}, R_{g} = 10 \text{ k}\Omega$
		_	_	1	dB	$V_{CE}$ = 6 V, $I_{C}$ = 0.1 mA, f = 1 kHz, $R_{g}$ = 10 kΩ

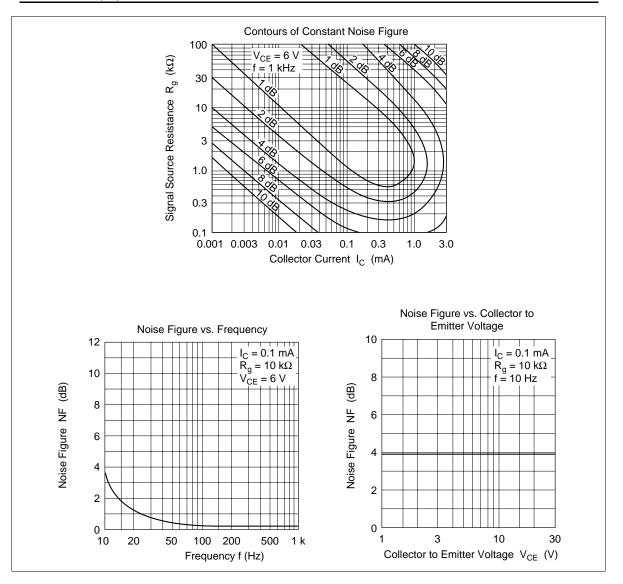
Note: 1. The 2SC1345(K) is grouped by  $h_{FE}$  as follows.

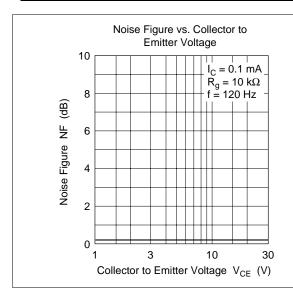
D	E	F
250 to 500	400 to 800	600 to 1200

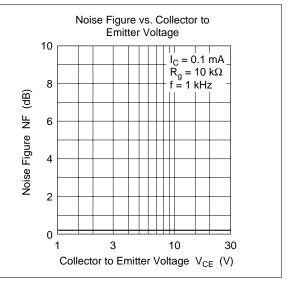




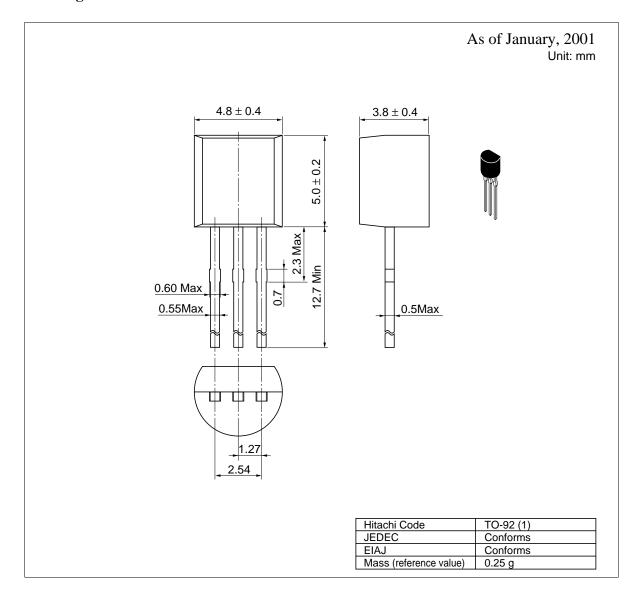








#### **Package Dimensions**



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